

 <b>Material Composition Declaration</b> © Copyright 2005, IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
1752-21.1		IPC Web Site for Information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>			Form Type * Distribute		Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information			
<b>Supplier Information</b>										
Company name* <b>onsemi</b>			Company unique ID			Unique ID Authority		Response Date* <b>2025-05-05</b>		
Contact Name <b>Product-Env-Stewards</b>			Title - Contact Product Enviro Compliance			Phone - Contact* <b>NA</b>		Email - Contact* <b>Product-Env-Stewards@onsemi.com</b>		
Authorized Representative* <b>Product-Env-Stewards</b>			Title - Representative Product Enviro Compliance			Phone - Representative* <b>NA</b>		Email - Representative* <b>Product-Env-Stewards@onsemi.com</b>		
	Requester Item Number	Mfr Item Number	Mfr Item Name		Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
		E8310-0-101A49-AG	E8310 Hybrid		2025-05-05		CA1	43.796642	mg	Each
<b>Manufacturing Process Information</b>										
	Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature		Max Time at Peak Temperature		Number of Reflow Cycles	
	<b>SnAgCu</b>	<b>CU Alloy</b>	<b>3</b>		<b>260</b> C		<b>30</b> seconds		<b>3</b>	
Comments										
<b>ATTENTION: MSL 3 Rated item requires Bake and Dry Pack (after electrical test)</b>										
<b>For more information regarding material composition please refer to page 3</b>										

RoHS Material Composition Declaration		Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).		
<p>Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a “RoHS restricted substance”) in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.</p>			
RoHS Declaration *	1 - Item(s) does not contain RoHS restricted substances per the definition above		Supplier Acceptance * Accepted
<b>Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.</b>			
Exemption List Version	EL-2011/534/EU		
Declaration Signature			
<b>Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.</b>			
Supplier Digital Signature	Rastislav Drska		

**Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Capacitor	0.113	mg	Supplier	Silicon Dioxide	7631-86-9		0.002	mg
			Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.023	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		0.0005	mg
			Supplier	Tin (Sn)	7440-31-5		0.0063	mg
			Supplier	Misc.	Proprietary Data		0.0077	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		0.0461	mg
			B	Nickel (Ni)	7440-02-0		0.0044	mg
			Supplier	Copper (Cu)	7440-50-8		0.023	mg
Die	3.085044	mg	Supplier	Silicon (Si)	7440-21-3		3.085	mg
Laminate Board	7.4432	mg		Lead Compound	n/a		0.0003	mg
			Supplier	Organic Compound	Proprietary Data		0.0703	mg
			Supplier	Organic Acid Salt	N/A		0.0057	mg
			Supplier	Inorganic Acid Salt	N/A		0.35	mg
			Supplier	Glass Cloth	65997-17-3		1.0662	mg
			Supplier	D.I. Water	7732-18-5		0.746	mg
			Supplier	copper foil	N/A		1.0567	mg
			Supplier	Organic Filler	N/A		0.0328	mg
			Supplier	Gold Potassium Cyanide	13967-50-5		0.1675	mg
			Supplier	Thermosetting resin	Proprietary Data		1.431	mg
			Supplier	Antifoamer and Leveling agent	Proprietary Data		0.0213	mg
			Supplier	Organic pigment	Proprietary Data		0.0025	mg
			Supplier	Phthalocyanine blue	147-14-8		0.0025	mg
			Supplier	Talc	14807-96-6		0.0459	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0004	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0164	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0001	mg
			B	Nickel (Ni)	7440-02-0		0.0002	mg
			Supplier	Cured Resin of Solder Mask	Proprietary Data		1.0087	mg
			Supplier	Copper (Cu)	7440-50-8		0.9114	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		0.5076	mg
Mold Compound-Black	30.8	mg		Epoxy resin	proprietary data		2.464	mg
			Supplier	Phenol Resin	Proprietary Data		1.54	mg

			Supplier	Metal Hydroxide	Proprietary Data		0.308	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		7.7	mg
			Supplier	Carbon Black (C)	1333-86-4		0.308	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		18.48	mg
Solder Paste	1.6942	mg	Supplier	2-(2-Hexyloxyethoxy) ethanol	112-59-4		0.0678	mg
			Supplier	Denatured Acid Hydrogenation Rosin	Proprietary		0.0678	mg
			Supplier	Dimer Acid	Proprietary		0.0339	mg
			Supplier	Silver (Ag)	7440-22-4		0.0508	mg
			Supplier	Tin (Sn)	7440-31-5		1.457	mg
			Supplier	Copper (Cu)	7440-50-8		0.0169	mg
Wire Bond - Au	0.6612	mg	Supplier	Gold (Au)	7440-57-5		0.6612	mg